



Material Content Data Sheet



Sales Product Name	TLE84106EL			Issued		28. August 2013		
MA#	MA000982454							
Package	PG-SSOP-24-4			Weight*		150.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.735	2.48	2.48	24780	24780
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8923	
	non noble metal	copper	7440-50-8	54.617	36.23	37.17	362315	371796
wire	noble metal	gold	7440-57-5	0.511	0.34	0.34	3390	3390
encapsulation	organic material	carbon black	1333-86-4	0.172	0.11		1144	
	plastics	epoxy resin	-	7.933	5.26		52625	
	inorganic material	silicondioxide	60676-86-0	78.122	51.83	57.20	518240	572009
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19310	19310
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1554	1554
glue	plastics	epoxy resin	-	0.270	0.18		1790	
	noble metal	silver	7440-22-4	0.810	0.54	0.72	5371	7161
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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